



Material Content Data Sheet



Sales Product Name	TLF4277-2LD			Issued	20. July 2018			
MA#	MA001504862							
Package	PG-TSON-10-2			Weight*	31.85 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.497	4.70	4.70	46988	46988
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		104	
	non noble metal	zinc	7440-66-6	0.013	0.04		417	
	non noble metal	iron	7439-89-6	0.265	0.83		8330	
wire	non noble metal	copper	7440-50-8	10.773	33.82	34.70	338229	347080
	non noble metal	copper	7440-50-8	0.040	0.13	0.13	1271	1271
	encapsulation	organic material	carbon black	1333-86-4	0.037	0.11		1148
	plastics	epoxy resin	-	1.883	5.91		59108	
	inorganic material	silicondioxide	60676-86-0	16.359	51.37	57.39	513610	573866
leadfinish	non noble metal	tin	7440-31-5	0.370	1.16	1.16	11620	11620
plating	noble metal	silver	7440-22-4	0.064	0.20	0.20	2018	2018
glue	plastics	epoxy resin	-	0.137	0.43		4289	
	noble metal	silver	7440-22-4	0.410	1.29	1.72	12868	17157
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com